

LS communication Thermocouple inputs: 7 -20 to 80 mV

#### **■**Summary



\*Number of inputs : 7 /Thermocouple input

(+1 /Cold junction compensation input,

Channel individual isolation)

**★Input range** : -20 to 80 mV

 $\star$  Module ambient temperature : -5 to 60°C

★Insulation method : Photocoupler insulation



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### **■**Specifications

	ITEM		SPECIFICATION
Input	Number of channels		7 points +1 point cold junction compensation (channel individual isolation)
·	Resolution		16 bits
	Burnout Upsca	le/Downscale	Switchable by EMS setting
	Range *1		-20 to 80 mV (Full Scale)
		TC	T: -200 to 400°C , -5.603 to 20.872 mV
			J: −200 to 1200°C , −7.890 to 69.553 mV
			E: -200 to 1000°C , -8.825 to 76.373 mV
			R: -50 to 1768°C , -0.226 to 21.101 mV
		5.75	K: -200 to 1372°C , -5.891 to 54.886 mV
Al. I.		RTD	PT100: -10 to 100°C , 96.09 to 138.51 Ω (Full Scale)
Absolute accuracy @25℃	mV	-	±0.1%FS (mV input)
	TC	Type-T	±4°C (<-150°C), ±1°C (-150°C~400°C)
		Type-J	±4°C (<-150°C), ±1°C (-150°C~1200°C)
		Туре-Е	±4°C (<-150°C), ±1°C (-150°C~1000°C)
		Type-R	±4°C (<0°C), ±3°C (0°C~200°C), ±2°C (>200°C)
		Type-K	$\pm 4^{\circ}$ C (<-150°C), $\pm 1^{\circ}$ C (-150°C~1372°C)
	RTD	Type-PT100	±0.1°C
Temperature drift			Less than ±100 ppm/°C (relative to full-scale)
@5℃ to 60℃	1112		Less than ±100 ppm/°C (relative to full-scale)
CMRR	TC	Type-E	100 dB or more attenuation
		Type-T	100 dB or more attenuation
	RTD	When voltage	100 dB or more attenuation
		When Current	100 dB or more attenuation
NMRR	TC		20 dB or more attenuation
	RTD		20 dB or more attenuation
Data refresh cycle			50 ms /All channels
Input filter			Software digital filter (Channel individual)
Dielectric strength			AC 500 V input terminal – between PE
Diolognio an engli			Between input channels
Communication with IOA Communication method Communication speed		method	LVDS
		n speed	100 Mbps
Self-diagnostic functions			Power voltage check (24 V, 3.3 V, 1.2 V)
			Clock check (FPGA-MCU for diagnosis, MCU for diagnosis -FPGA)
			Heartbeat check (FPGA-MCU for diagnosis, MCU for diagnosis -FPGA)
			CRC check (FPGA)
			Al communication error check
Detective			ADC abnormal check
			I/O signal range check (Overrange, Underrange) *1
Operation at disconnection			1 to 7 ch (For upscale burnout setting) Detect overrange 1 to 7 ch (For downscale burnout setting)Detect underrange
			8 ch Simultaneous detection of underrange and overrange
Protection	1,-		Overvoltage protection
Totection	(Power supply protection)		Overcurrent protection
Indicator	Display LED		4: RUN (Run) / STS (Status) /NSA (Network status A) / NSB (Network status B)
Insulation method			Photocoupler insulation
Hot swap			Possible
Power supply			DC 24 V ±20% (The voltage supplied from the backplane)
Environmental conditions Module ambient temperature		t tomporative	(Operating) -5 to 60°C
	ivioquie ambient temperature		(Storage) -40 to 85°C
	Module ambier	t humidity	(Operating / Storage) Less than 95% RH (No condensation)
Vibration			3.5 mm @5 to 8.4 Hz
			1 G @8.4 to 150 Hz
Shock			15 G 11 ms
Current consumption			Less than 68 mA
Weight			0.10 kg
Dimensions			62 mm (D) x 94 mm (H) x 46 mm (W) (Except projection)
Standard/Directive			EN 61131-2:2007, RoHS



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#### About compliant module type

For compliant modules of this product, please refer to "Compliant backplane list (CGS-S9901-E-XX)".

For compliant modules of this product, please refer to "Compliant accessory connector list (CGS-S9902-E-XX)".

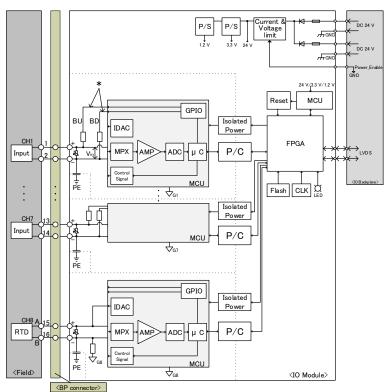
- $st^1$  Input Overrange / Input Underrange are detected under the following conditions.
  - ·Type-E: Less than -270°C (-9.835mV) / More than 1000°C (36.373mV)
  - ·Type-J: Less than -210°C (-8.095mV) / More than 1200°C (69.553mV)
  - ·Type-K: Less than  $-270^{\circ}$ C (-6.458mV) / More than  $1370^{\circ}$ C (54.819mV)
  - ·Type-R: Less than -50°C (-0.226mV) / More than 1760°C (21.003mV)
  - $\cdot$ Type-T: Less than -270°C (-6.258mV) / More than 400°C (20.872mV)
  - ·Pt100 : Less than -12.77°C (95.000Ω) / More than 103.072°C (139.670Ω)





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#### **■**Block diagram



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The setting of burnout direction ,upscale / downscale, is determined by which side of + side / - side is made High.

- •Normal time: The electromotive force of the compensation conductor is input to the MCU at Vin (+/- line voltage)
- -At the time of disconnection (upscale burnout setting): the potential of the + side wiring rises  $\Rightarrow$

The value of Vin (the difference between the + side and the - side) becomes too large. (The ADC input sticks to the upper limit)  $\Rightarrow$  Overrange

-At the time of disconnection (downscale burnout setting): the potential of the - side wiring rises  $\Rightarrow$ 

The value of Vin (the difference between the + side and the - side) becomes too small. (The ADC input sticks to the lower limit)  $\Rightarrow$  Underrange

P/S : Power supply

IDAC : lout Digital analog converter

MPX : Multiplexer AMP : Amplifier

ADC : Analog digital converter

 $\mu$  C : Micro controller

CLK : Clock

FPGA : Field programmable gate array

LED : Light emitting diode MCU : Micro control unit

GND,G1 : Ground IOA : I/O adapter

LVDS : Low Voltage Differential Signaling

BP : Backplane
PE : Protective Earth
P/C : Photocoupler
: Varistor
: Resistor
: Fuse
: Diode
: Capacitor

When using, please read the instruction manual attached to the product carefully and use it properly.

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